

Section

MV Semi-conductor

ApplicationField
Production**PRODUCT BENEFITS**

4 adjustable scoring depth
Easy catch of the semicon
Light

TOOL CAPACITY

Diameter	10 - 100 mm 0,394 - 3,937 inch
Scoring depth	0.4 / 0.6 / 0.9 / 1.1 mm 0.016 / 0.024 / 0.035 / 0.043 inch
Min remaining length	10 mm

TOOL DIMENSIONS

Length	135 mm
Width	55 mm
Height	35 mm
Weight without box	0,16 Kg
Packaging	Box

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Tool to perform controlled longitudinal scoring on peelable semiconductor

TO DO WHAT

L'ORACL permet d'inciser longitudinalement le semi-conducteur pelable pour ensuite le retirer à la main.

Profondeur d'incision réglable (0.4 / 0.6 / 0.9 / 1.1 mm)

**Spare part**

LSO - Spare blade for peelable semiconductor

Associated tool

DSP - Peelable semiconductor lifter
MVS - Stop for tools

MV cables Tools
ORACL



Part Number	Diameter	Tool capacity		Dimensions			Packaging
		Scoring depth	Min remaining length	Length	Width	Height	
ORACL	10 - 100 mm 0,394 - 3,937 in	0.4 / 0.6 / 0.9 / 1.1 mm 0.016 / 0.024 / 0.035 / 0.043 inch	10 mm	135 mm 5,315 in	55 mm 2,165 in	35 mm 1,378 in	box